

AN

===== WPI =====

TI - Injection moulding process - which blows cold gas at lower temp. than first gas injection process to accelerate prod. cooling

AB - JP6091686 Injection moulding comprises an injection process to inject melted resin to the cavity of mould from a nozzle of plasticising cylinder, the first gas injection process to form a hollow part at the inside of melted resin injected in the cavity forming a gas passage by blowing gas from the nozzle of cylinder and second gas injection process to blow gas to the hollow part from the gas injection appts. having a gas outlet opened to the cavity to flow gas to the reverse direction of gas flow from the nozzle of plasticising cylinder to discharge gas from the nozzle.

- USE/ADVANTAGE - To reduce moulding cycles by blowing gas colder than the gas flowed at the first gas injection process to accelerate cooling of prods. (Dwg. 0/13)

PN - JP6091686 A 19940405 DW199418 B29C45/00 009pp
 - JP2816280B2 B2 19981027 DW199848 B29C45/00 009pp

PR - JP19920270903 19920914

PA - (DAIH-N) DAIHO KOGYO KK

MC - A11-B10 A11-B12

DC - A32

IC - B29C45/26 ;B29C49/06 ;B29C49/58 ;B29L22/00

AN - 1994-147365 [18]

===== PAJ =====

TI - GAS INJECTION MOLDED PRODUCT AND GAS INJECTION MOLDING METHOD AND APPARATUS

AB - PURPOSE: To shorten an injection molding cycle time by forming a cavity in a resin by gas and injecting low temp. gas into the cavity from a gas injection device to cool the resin from the interior of the cavity.

- CONSTITUTION: A gas injection device 30 is incorporated in a movable mold 10. A resin is injected into a cavity 20 from a cylinder nozzle and, subsequently, high pressure gas is blown in the resin from a nozzle to form a hollow part 21 in the resin received in the cavity 20. Next, gas whose temp. is lower than that of the high pressure gas from the nozzle is injected into the hollow part 21 from the gas injection device and a changeover valve 26b is changed over to discharge the gas in the hollow part 21 and the hollow part 21 is filled with the low temp. gas from the gas injection device 30. Therefore, the resin in the cavity 20 is cooled from the hollow part 21 and the cooling time of the resin becomes short. Since gas injection can be performed from the cylinder nozzle and the gas injection device 30, an injection molding cycle time can be shortened.

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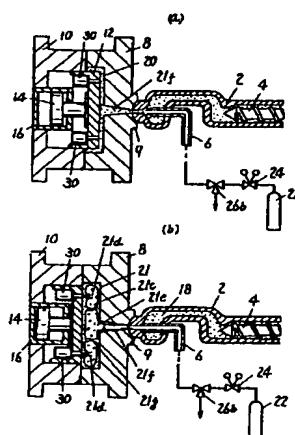
GR - M1632

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